

Amendments to the Specification

Please replace paragraphs [0030] and [0031] with the following amended paragraphs:

[0030] In a typical embodiment, the thickness of the package substrate is approximately 0.1 mm, the height of the solder balls measured from the substrate surface is approximately 0.3 mm, and the height of the die is approximately 0.18 mm; this gives an overall package height of approximately 0.4 mm. Further reductions in these dimensions are possible, so that overall package heights [[les than]] less than 0.4 mm can be obtained according to the invention.

[0031] Moreover, the length of the longest conductive traces can be [[less that]] less than 1.0 mm in an embodiment having [[to]] two peripherally arranged rows of solder balls at a 0.5 mm pitch. This can provide exceptionally high electrical performance.